

WHAT IS CLAIMED IS:

1. An electronic-circuit unit comprising:  
an alumina board;  
circuit elements comprising a capacitor, a resistor,  
and an inductive device, are formed as thin films on the  
alumina board;  
an electrically conductive pattern connected to at  
least one circuit element is formed as a thin film on the  
alumina board;  
a semiconductor bare chip is mounted on the alumina  
board; and  
an end-face electrode connected to the electrically  
conductive pattern is formed on a side face of the alumina  
board,  
wherein the semiconductor bare chip is wire-bonded to  
the electrically conductive pattern.
2. An electronic-circuit unit according to Claim 1,  
wherein a Cu layer is formed on a surface of the capacitor  
and the inductive device.
3. An electronic-circuit unit according to Claim 1,  
wherein the end-face electrode is formed as a thick film by  
the use of a low-temperature baked material.
4. An electronic-circuit unit according to Claim 3,

wherein an Au plating layer is formed on the end-face electrode.

5. An electronic-circuit unit according to Claim 3, wherein the end-face electrode is formed as a thick film only at each of two sides along opposing edges of the alumina board.

6. An electronic-circuit unit according to Claim 4, wherein the end-face electrode is formed as a thick film only at each of two sides along opposing edges of the alumina board.

7. An electronic-circuit unit comprising:  
circuit element comprising a capacitor, a resistor, and an inductive device, formed as thin films on an alumina board having a rectangular, plane shape;

a semiconductor bare chip wire-bonded on the alumina board;

grounding electrodes formed at the ends of two sides along opposing edges of the alumina board; and

an input electrode and an output electrode formed away from the ends.

8. An electronic-circuit unit according to Claim 7, wherein a shielding cover is mounted to the alumina board so as to cover the circuit elements and the

semiconductor bare chip, the shielding cover being soldered to the grounding electrodes.